

MEGIC-01-013B

January 14, 2004

To: Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Fr: George O. Saile, Reg. No. 19,572  
28 Davis Avenue  
Poughkeepsie, N.Y. 12603

Subject:

Serial No. 10/690,350 10/21/03

Mou-Shiung Lin et al.

THIN FILM SEMICONDUCTOR PACKAGE  
AND METHOD OF FABRICATION

#### INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation  
In An Application.

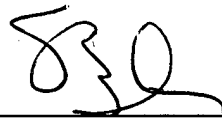
The following Patents and/or Publications are submitted to  
comply with the duty of disclosure under CFR 1.97-1.99 and  
37 CFR 1.56. Copies of each document is included herewith.

#### CERTIFICATE OF MAILING

I hereby certify that this correspondence is being  
deposited with the United States Postal Service as first class  
mail in an envelope addressed to: Commissioner for Patents,  
P.O. Box 1450, Alexandria, VA 22313-1450, on January 27, 2004.

Stephen B. Ackerman, Reg.# 37761

Signature/Date

 1/27/04

The following two publications relate to the use of thin

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films in the interconnection and packaging of semiconductor dies:

- 1) Microelectronic Packaging Handbook, Chapter 9, R.R. Tummala et al., Van Nostrand Reinhold, NY, 1989, pp. 673-725.
- 2) Novel Microelectronic Packaging Method for Reduced Thermomechanical Stresses on Low Dielectric Constant Materials, R.M. Emery et al., Intel Corp., Chandler, AZ.

Sincerely,



Stephen B. Ackerman,  
Reg. No. 37761

Application Number:

10/690,350

Mou-Shiung Lin et al.

10 / 24 / 03

Group Art Unit



(so several sheets if necessary)

## U. S. PATENT DOCUMENTS

[illegible]

## FOREIGN PATENT DOCUMENTS

[illegible]

OTHER DOCUMENTS (Including Author, Title, Date, Portion, Pages, Etc.)

- Microelectronic Packaging Handbook, Chapter 9, R.R. Tummala et al., Van Nostrand Reinhold, NY, 1989, pp. 673-725.
- Novel Microelectronic Packaging Method for Reduced Thermomechanical Stresses on Low Dielectric Constant Materials, R.M. Emery, et al., Intel Corp., Chandler, AZ.

DATE CONSIDERED

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.